

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



April 2015

FDC8886

N-Channel Power Trench[®] MOSFET 30 V, 6.5 A, 23 m Ω

Features

- Max $r_{DS(on)}$ = 23 m Ω at V_{GS} = 10 V, I_D = 6.5 A
- Max $r_{DS(on)}$ = 36 m Ω at V_{GS} = 4.5 V, I_D = 6.0 A
- High performance trench technology for extremely low r_{DS(on)}
- Fast switching speed
- RoHS Compliant

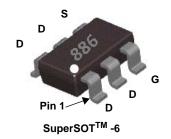


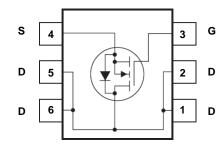
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$ switching performance.

Application

■ Primary Switch





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

| Symbol | Parameter | | Ratings | Units |
|-----------------------------------|--|-----------|-------------|-------|
| V _{DS} | Drain to Source Voltage | | 30 | V |
| V_{GS} | Gate to Source Voltage | (Note 3) | ±20 | V |
| | Drain Current -Continuous (Package limited) T _C = 25 °C | | 8.0 | |
| I _D | -Continuous T _A = 25 °C | (Note 1a) | 6.5 | Α |
| | -Pulsed | | 25 | |
| В | Power Dissipation | (Note 1a) | 1.6 | W |
| P_{D} | Power Dissipation | (Note 1b) | 0.8 | VV |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | | -55 to +150 | °C |

Thermal Characteristics

| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 30 | °C/W |
|-----------------|---|----|------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient (Note 1a) | 78 | C/VV |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|---------|---------|-----------|------------|------------|
| .886 | FDC8886 | SSOT-6 | 7 " | 8 mm | 3000 units |

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|--------------------------------------|--|---|-----|-----|-----|-------|
| Off Chara | acteristics | | | | | |
| BV _{DSS} | Drain to Source Breakdown Voltage | $I_D = 250 \mu A, V_{GS} = 0 V$ | 30 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | I _D = 250 μA, referenced to 25 °C | | 18 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 24 V, V _{GS} = 0 V | | | 1 | μΑ |
| I _{GSS} | Gate to Source Leakage Current, Forward | V _{GS} = 20 V, V _{DS} = 0 V | | | 100 | nA |

On Characteristics

| V _{GS(th)} | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 250 \mu A$ | 1.2 | 1.9 | 3.0 | V |
|--|--|--|-----|-----|-----|-------|
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate to Source Threshold Voltage Temperature Coefficient | $I_D = 250 \mu A$, referenced to 25 °C | | -6 | | mV/°C |
| r _{DS(on)} | | $V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$ | | 19 | 23 | |
| | Static Drain to Source On Resistance | $V_{GS} = 4.5 \text{ V}, I_D = 6.0 \text{ A}$ | | 30 | 36 | mΩ |
| , , | | $V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}, T_J = 125 ^{\circ}\text{C}$ | | 25 | 30 | |
| 9 _{FS} | Forward Transconductance | V _{DD} = 5 V, I _D = 6.5 A | | 24 | | S |

Dynamic Characteristics

| C _{iss} | Input Capacitance | V 45.V.V 0.V | 348 | 465 | pF |
|------------------|------------------------------|---|-----|-----|----|
| C _{oss} | Output Capacitance | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz | 135 | 180 | pF |
| C _{rss} | Reverse Transfer Capacitance | 1 - 1 101112 | 16 | 25 | pF |
| R_a | Gate Resistance | | 1.2 | | Ω |

Switching Characteristics

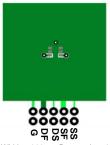
| t _{d(on)} | Turn-On Delay Time | | 5 | 10 | ns |
|---------------------|-------------------------------|---|-----|-----|----|
| t _r | Rise Time | V_{DD} = 15 V, I_{D} = 6.5 A, V_{GS} = 10 V, R_{GEN} = 6 Ω | 1 | 10 | ns |
| t _{d(off)} | Turn-Off Delay Time | | 11 | 19 | ns |
| t _f | Fall Time | | 1 | 10 | ns |
| 0 | Total Gate Charge | V _{GS} = 0 V to 10 V | 5.3 | 7.4 | nC |
| $Q_{g(TOT)}$ | Total Gate Charge | $V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$ | 2.5 | 3.5 | nC |
| Q_{gs} | Total Gate Charge | I _D = 6.5 A | 1.0 | | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | | 0.8 | | nC |

Drain-Source Diode Characteristics

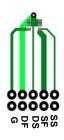
| V_{SD} | Source to Drain Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_S = 6.5 \text{ A}$ (Note 2) | 0.86 | 1.2 | V |
|-----------------|---------------------------------------|--|------|-----|----|
| t _{rr} | Reverse Recovery Time | I _E = 6.5 A, di/dt = 100 A/μs | 14 | 22 | ns |
| Q _{rr} | Reverse Recovery Charge | TIF = 0.5 A, α//αι = 100 A/μS | 3 | 10 | nC |

NOTES

 $^{1.}R_{0,\mathrm{MA}}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{0,\mathrm{MC}}$ is guaranteed by design while $R_{0,\mathrm{CA}}$ is determined by the user's board design.



a. 78 °C/W when mounted on a 1 in² pad of 2 oz copper



b.175 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0 %.
- 3. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

Typical Characteristics T_J = 25 °C unless otherwise noted

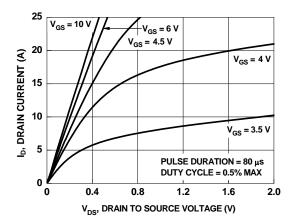
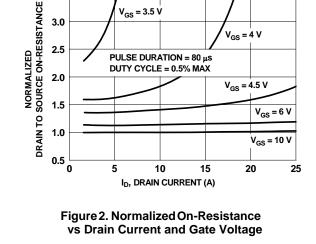


Figure 1. On Region Characteristics



3.5

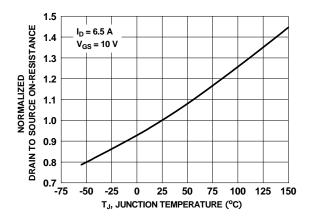


Figure 3. Normalized On Resistance vs Junction Temperature

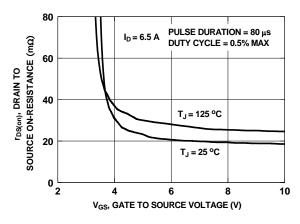


Figure 4. On-Resistance vs Gate to Source Voltage

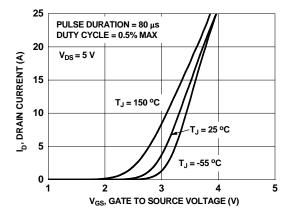


Figure 5. Transfer Characteristics

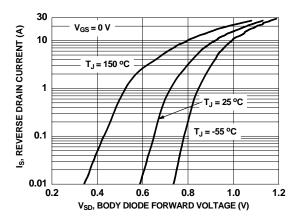


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

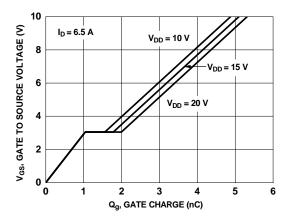


Figure 7. Gate Charge Characteristics

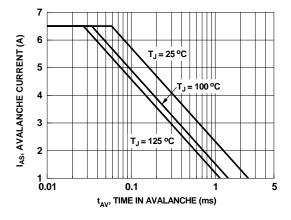


Figure 9. Unclamped Inductive Switching Capability

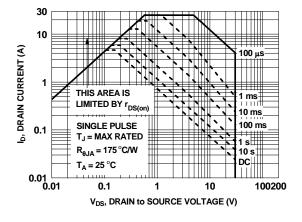


Figure 11. Forward Bias Safe Operating Area

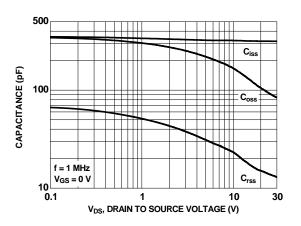


Figure 8. Capacitance vs Drain to Source Voltage

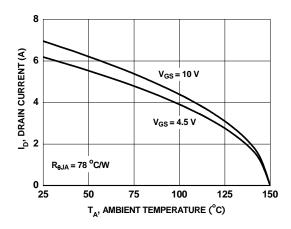


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

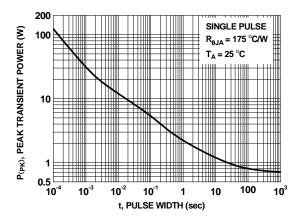


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

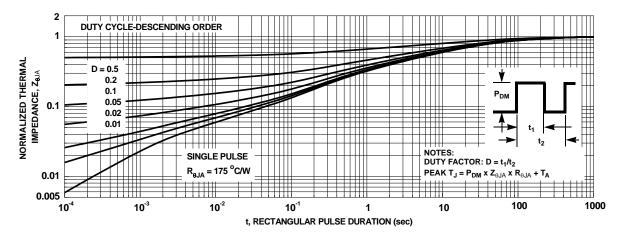
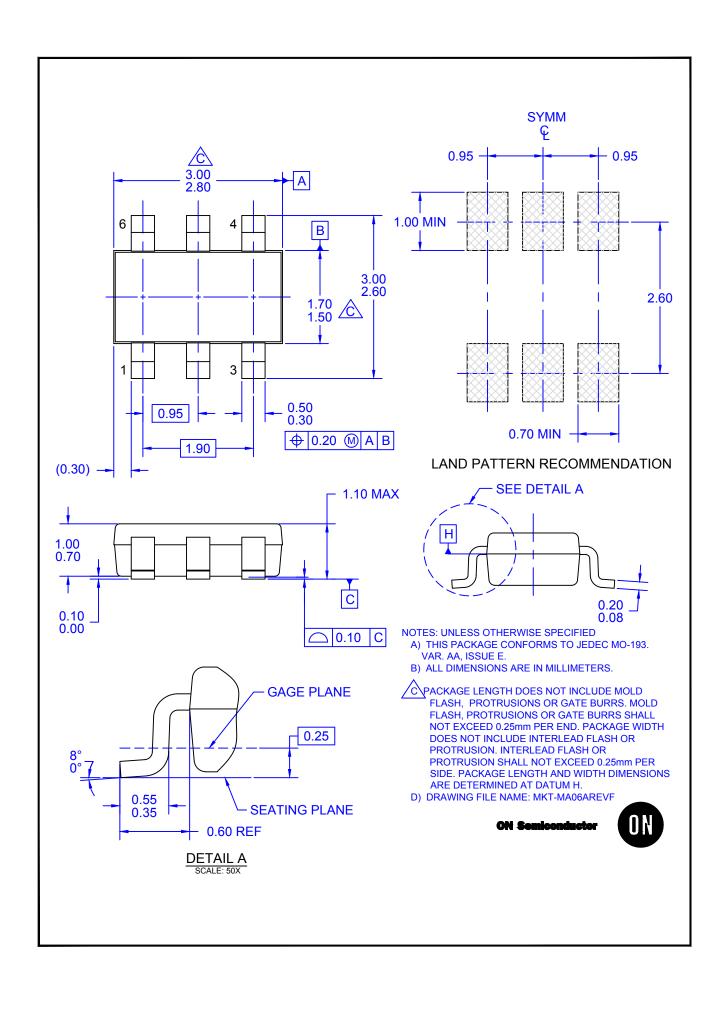


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see any inability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and ex

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

FDC8886

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

многоканальный

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9